

PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Nishant Sinha

Serial No.: 10/668,914

Filed: September 23, 2003

**For: PROCESS AND INTEGRATION
SCHEME FOR FABRICATING
CONDUCTIVE COMPONENTS,
THROUGH-VIAS AND
SEMICONDUCTOR COMPONENTS
INCLUDING CONDUCTIVE THROUGH-
WAFER VIAS**

Confirmation No.: 2525

Examiner: Unknown

Group Art Unit: 2812

Attorney Docket No.: 2269-5859US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

February 4, 2004
Date

Signature _____

Shirley D. Dougherty
Name (Type/Print)

PRELIMINARY AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

Amendments to the Specification appear on page 2 of this paper.

Amendments to the Claims are reflected in the listing which begins on page 8 of this paper.

Remarks begin on page 16 of this paper.